


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	[BUMP PROCESS FOR FLIP CHIP PACKAGE]		
Application Type : regular, utility Attorney Docket Number : 10665-US-PA			
Correspondence address: Customer Number: 31561 			
Priority Data: Doc.No: 92114347; Country -TW ; Date: 2003-05-28 us-priority-claimed			
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.